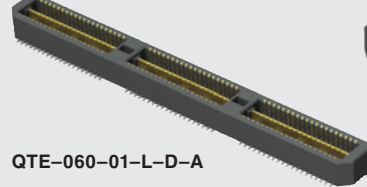
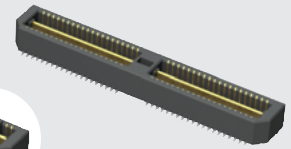




QTE-014-01-F-D-DP-A



QTE-060-01-L-D-A



QTE-040-01-L-D-A

(0,80 mm) .0315"

QTE SERIES

# HIGH SPEED GROUND PLANE HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?QTE](http://www.samtec.com?QTE)

**Insulator Material:**

Liquid Crystal Polymer

**Terminal Material:**

Phosphor Bronze

**Plating:** Au or Sn over 50µ" (1,27 µm) Ni

**Current Rating:**

Contact:

2 A per pin

(1 pin powered per row)

Ground Plane:

23 A per ground plane

(1 ground plane powered)

**Operating Temp Range:**

-55°C to +125°C

**Voltage Rating:**

225 VAC mated with QSE & 5 mm Stack Height

**Max Cycles:** 100

**RoHS Compliant:** Yes

**Processing:**

**Lead-Free Solderable:** Yes

**SMT Lead Coplanarity:**

(0,10 mm) .004" max (020-060)

**Board Stacking:**

For applications requiring more than two connectors per board contact [ipg@samtec.com](mailto:ipg@samtec.com)

**Board Mates:**

QSE

**Cable Mates:**

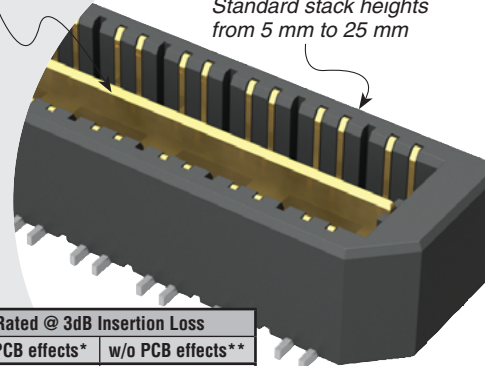
EQCD, EQDP, EQRF

(See Also Available note)



Integral metal plane for power or ground

Standard stack heights from 5 mm to 25 mm



### Protocols Supported

- 100 GbE
- XAUI
- PCI Express®
- SATA
- MGT (Rocket I/O)
- InfiniBand™

Download app notes at [www.samtec.com/appnote](http://www.samtec.com/appnote)  
Contact [SIG@samtec.com](mailto:SIG@samtec.com) for questions on protocols

QTE/QSE 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	9 GHz / 18 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	14 GHz / 28 Gbps
Differential Pair Signaling	-DP	8.5 GHz / 17 Gbps	13.5 GHz / 27 Gbps

\*Performance data includes effects of a non-optimized PCB.

\*\*Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at [www.samtec.com?QTE](http://www.samtec.com?QTE) or contact [sig@samtec.com](mailto:sig@samtec.com)

**infinch**  
CERTIFIED

28+  
Gbps



-020, -040, -060  
(40 total pins per bank = -D)

-014, -028, -042  
(14 pairs per bank = -D-DP)

Specify LEAD STYLE from chart

-F  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L  
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C\*  
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-D  
= Single-Ended

-D-DP  
= Differential Pair (-01 only)

-K  
= (7,00 mm) .275" DIA Polyimide Film Pick & Place Pad

-TR  
= Tape & Reel Packaging (N/A on -05 & -07 lead style)

-L  
= Latching Option (N/A on -042 & -060 positions)

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4,27) .168	(5,00) .197
-02	(7,26) .286	(8,00) .315
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,26) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

\*Processing conditions will affect mated height.

## OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series

## RECOGNITIONS

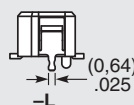
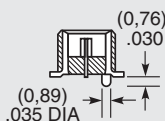
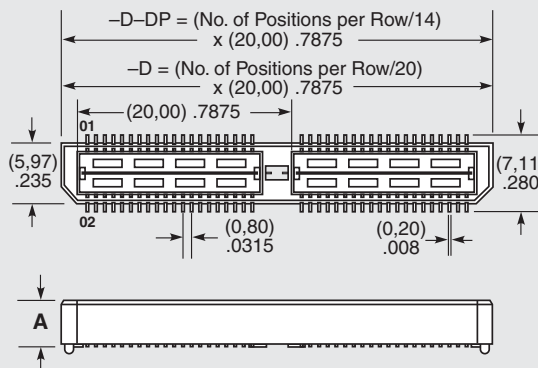
For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594 FILE NO. 090971\_0\_000

## ALSO AVAILABLE (MOQ Required)

- 14 mm, 15 mm, 22 mm and 30 mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76 µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount
- 56 (-DP), 80, 100 positions per row
- Guide Posts, Screw Down & Friction Lock
- Retention Option
- Contact Samtec.



\*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.